SV05..F

Fast Recovery Diode

Replaces January 2000 version, DS4144-4.0

DS4144-5.0 June 2004

APPLICATIONS

- Induction Heating
- A.C. Motor Drives
- Snubber Diode
- Welding
- High Frequency Rectification
- UPS

KEY PARAMETERS

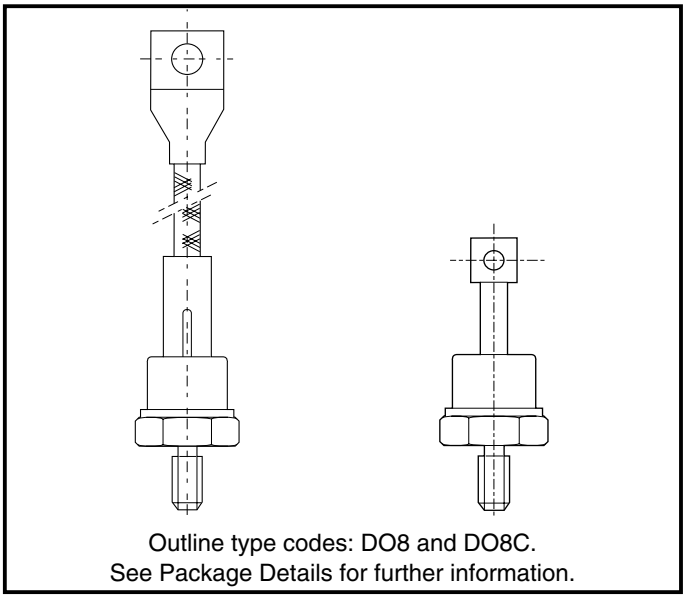
V_{RRM}	2500V
$I_{F(AV)}$	145A
I_{FSM}	2500A
Q_r	150µC
t_{rr}	2.2µs

FEATURES

- Double Side Cooling
- High Surge Capability
- Low Recovery Charge

VOLTAGE RATINGS

Type Number	Repetitive Peak Reverse Voltage V_{RRM} V	Conditions
SV05 25F M or K	2500	$V_{RSM} = V_{RRM} + 100V$
SV05 24F M or K	2400	
SV05 22F M or K	2200	
SV05 20F M or K	2000	



Outline type codes: DO8 and DO8C.
See Package Details for further information.

Fig. 1 Package outlines

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table, e.g.:

SV05 24FM for an M12 thread

or

SV05 24FK for a 1/2" 20 UNF thread

For stud anode add 'R' to type number, e.g. **SV05 25FMR**.
For outline DO8C add suffix 'C' to typ number,
e.g. **SV05 25FKC**.

Note: Please use the complete part number when ordering and quote this number in any future correspondance relating to your order.

CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{F(AV)}$	Mean forward current	Half wave resistive load, T_{case} = 65°C	145	A
$I_{F(RMS)}$	RMS value	T_{case} = 65°C	225	A
I_F	Continuous (direct) forward current	T_{case} = 65°C	195	A

SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; with 0% V_{RRM}, T_j = 150°C	2.5	kA
I^2t	I^2t for fusing		31×10^3	A^2s
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; with 50% V_{RRM}, T_j = 150°C	2.0	kA
I^2t	I^2t for fusing		20×10^3	A^2s

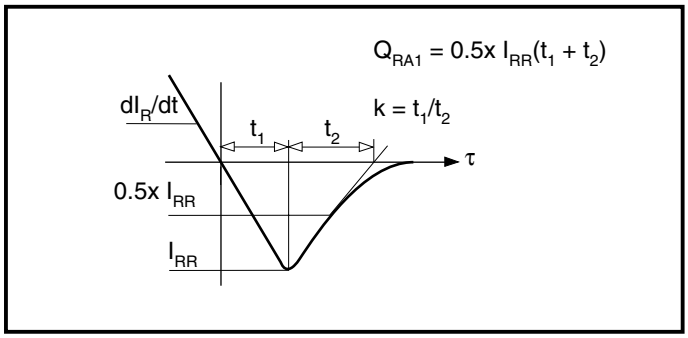
THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case	dc	-	0.23	°C/W
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Mounting torque 15Nm with mounting compound	-	0.02	°C/W
T_{vj}	Virtual junction temperature	On-state (conducting)	-	150	°C
T_{stg}	Storage temperature range		-55	150	°C
-	Mounting torque		13.5	16.5	Nm

CHARACTERISTICS

Symbol	Parameter	Conditions	Typ.	Max.	Units
V_{FM}	Forward voltage	At 600A peak, T_{case} = 25°C	-	2.8	V
I_{RRM}	Peak reverse current	At V_{RRM}, T_{case} = 150°C	-	50	mA
t_{rr}	Reverse recovery time	I_F = 600A, di_{RR}/dt = 80A/µs T_{case} = 150°C, V_R = 100V	2.2	-	µs
Q_{RA1}	Recovered charge (50% chord)		-	150	µC
I_{RM}	Reverse recovery current		-	140	A
V_{TO}	Threshold voltage	At T_{vj} = 150°C	-	1.4	V
r_T	Slope resistance	At T_{vj} = 150°C	-	2.5	mΩ
V_{FRM}	Forward recovery voltage	di/dt = 1000A/µs, T_j = 125°C	-	250	V

DEFINITION OF K FACTOR AND Q_{RA1}



CURVES

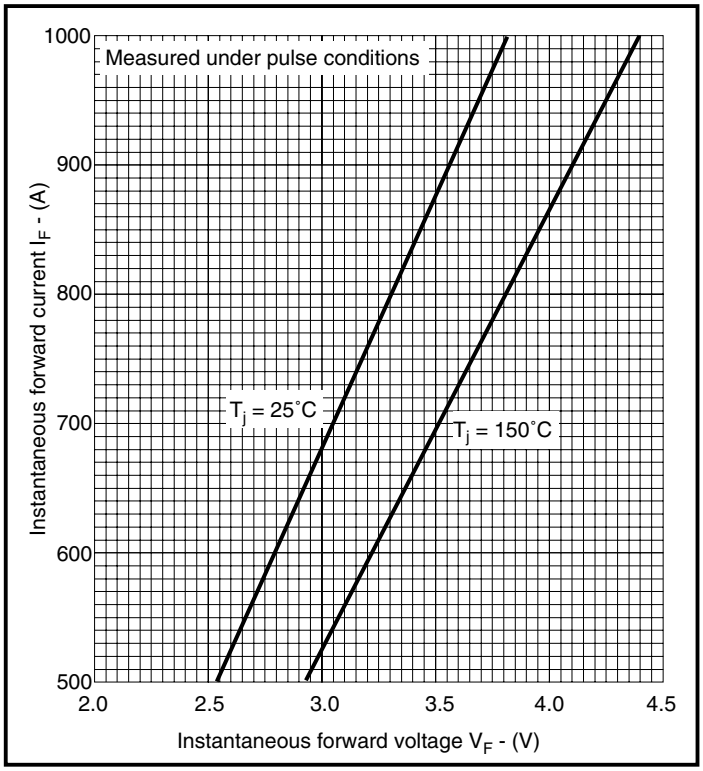


Fig.2 Maximum (limit) forward characteristics

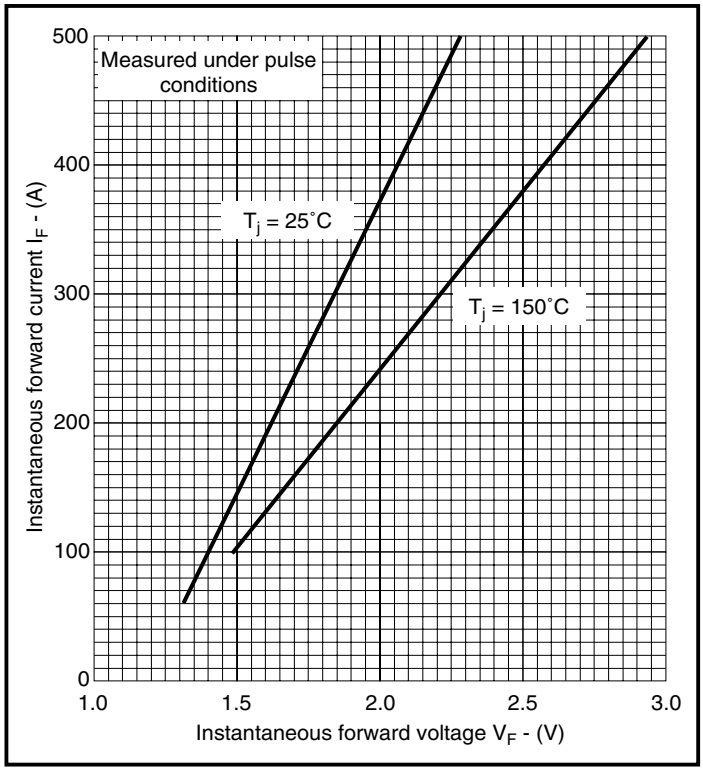


Fig.3 Maximum (limit) forward characteristics

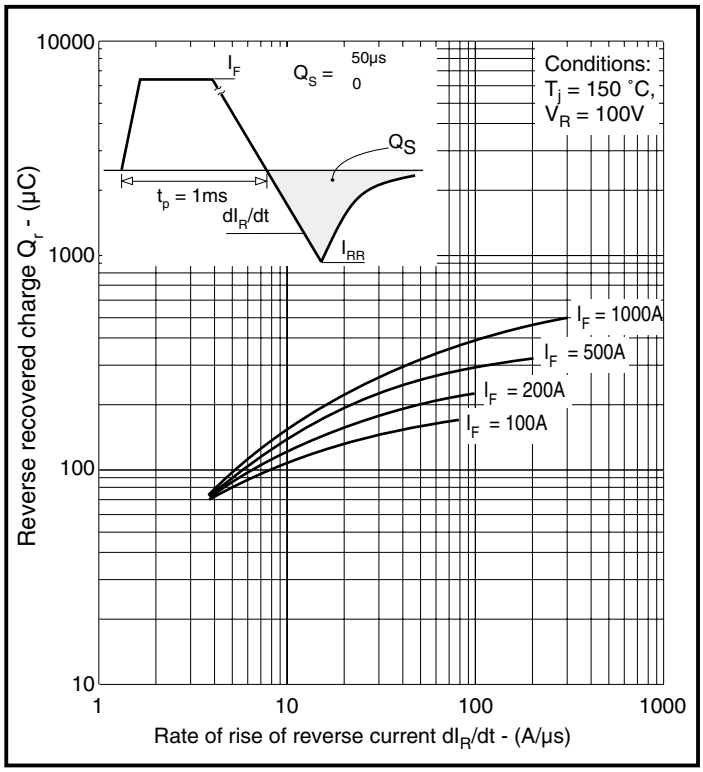


Fig.4 Recovered charge

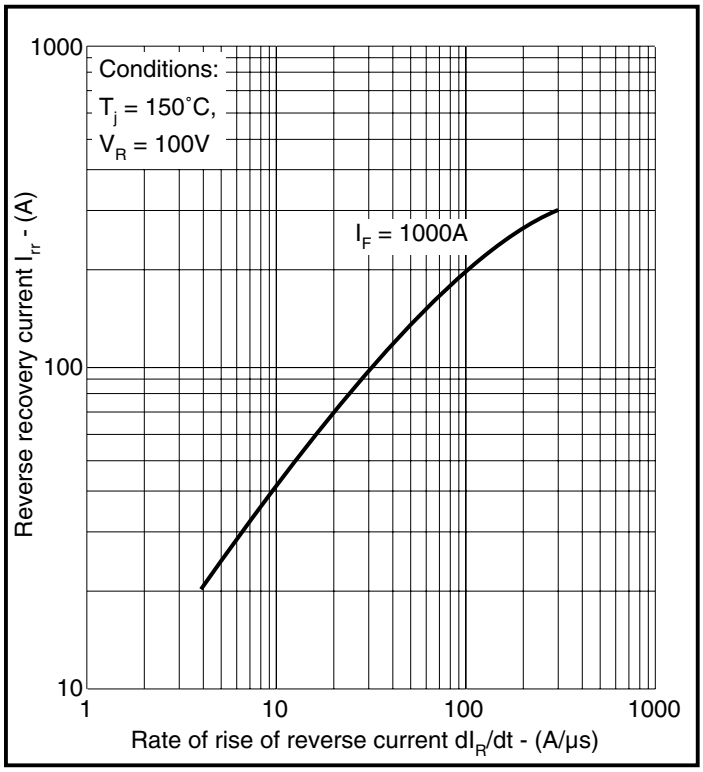


Fig.5 Typical reverse recovery current vs rate of rise of forward current

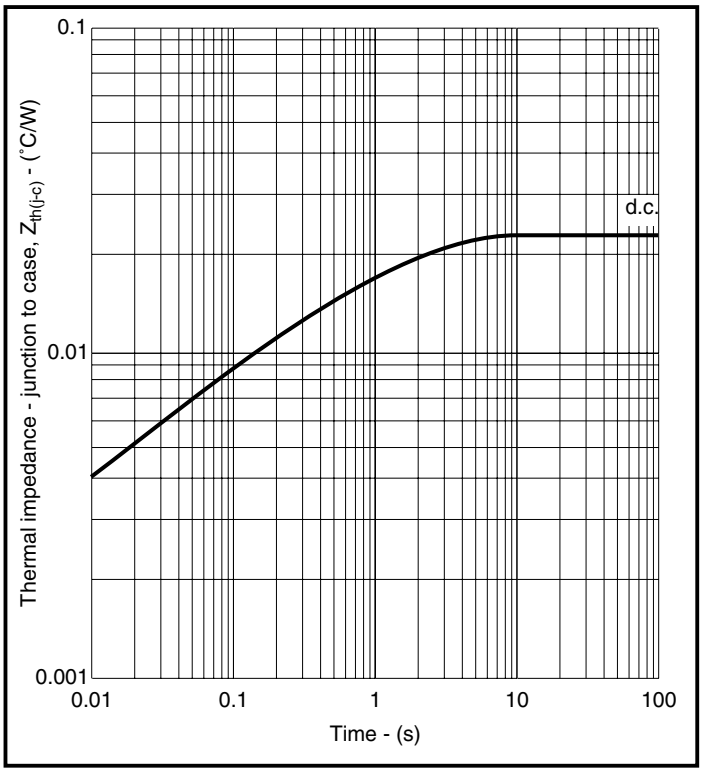
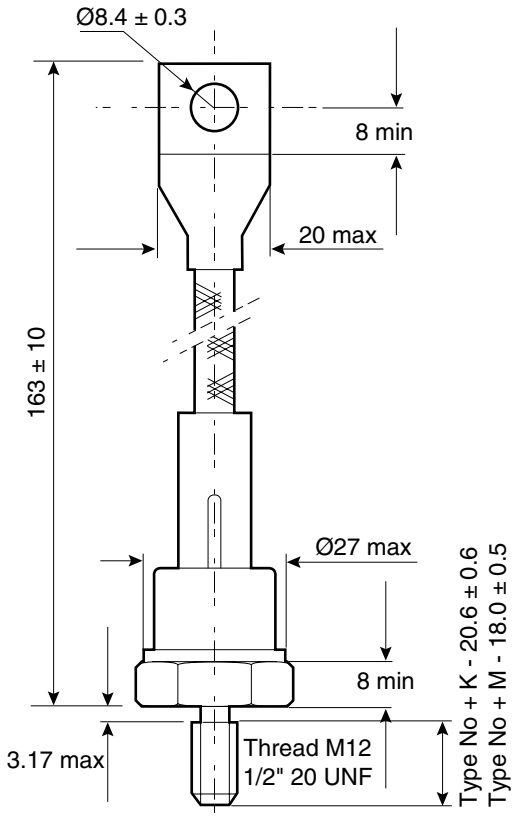


Fig.6 Maximum (limit) transient thermal impedance - junction to case - (˚C/W)

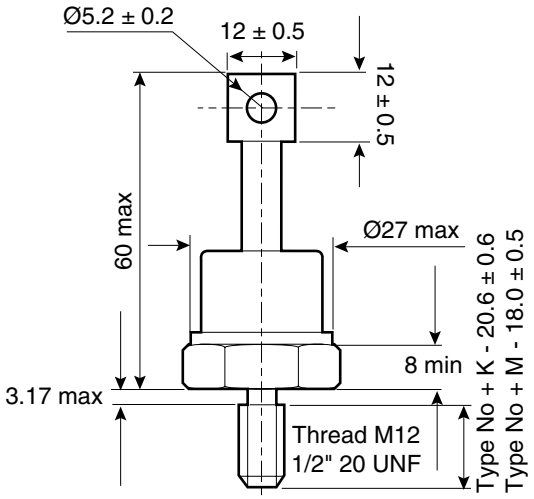
PACKAGE DETAILS - DO8 and DO8C

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise.
DO NOT SCALE.



Nominal weight: 120g
Mounting torque: 15Nm ±10%

Package outline type code: DO8



Nominal weight: 120g
Mounting torque: 15Nm ±10%

Package outline type code: DO8C

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.

Stresses above those listed in this data sheet may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed.

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